

Electronic Patent Application Fee Transmittal

Application Number:	
Filing Date:	
Title of Invention:	MULTILAYER SUBSTRATE WITH BUILT-IN CHIP-TYPE ELECTRONIC COMPONENT AND METHOD FOR MANUFACTURING THE SAME
First Named Inventor:	Osamu CHIKAGAWA
Filer:	Stephen Russell Funk/Allison Cowan
Attorney Docket Number:	36856.1458

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
National Stage Fee	1631	1	300	300
Natl Stage Search Fee - Report provided	1642	1	400	400
National Stage Exam - all other cases	1633	1	200	200

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Miscellaneous:				
			Total in USD (\$)	900